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TABLE OF CONTENTS

Compact Monolithic Arrayed Optical Receivers for Ultra-High Density Photonic Interconnects	1
<i>Robert P. Pesch, Joshua J. Wong, Stephen E. Ralph</i>	
Integrated Optical and Electrical Connectivity in Advanced Packaging: The Role of Glass Substrates	3
<i>Lucas W. Yeary, Lars Brusberg, Jason R. Grenier</i>	
Longitudinal-Mode Photon-Photon Resonances in Multiple-Cavity Distributed-Feedback Lasers and Vertical-Cavity Surface-Emitting Lasers	5
<i>Jack Jewell</i>	
Seeding, Filtering, and Inverse Design for Commercial Foundry Photonics	7
<i>Joshua J. Wong, Jacob M. Hiesener, Robert P. Pesch, Stephen E. Ralph</i>	
Advanced VCSEL Integration and Assembly Technologies.....	9
<i>Luke A. Graham, James K. Guenter, Pritha Khurana, Jim A. Tatum</i>	
One-Step Fabrication of Mirco-Mirror Based 3D Polymer Optical Link for Co-Packaged Optics Using Imprint Technology.....	11
<i>Fumi Nakamura, Kenta Suzuki, Akihiro Noriki, Satoshi Suda, Takayuki Kurosu, Takeru Amano</i>	
Scalable and Monolithic Integration of Quantum Dot Lasers for Silicon Photonics.....	13
<i>Bei Shi, Rosalyn Koscica, Alec Skipper, Simone Suran Brunelli, Gerald J. Leake, Joshua Herman, David Harame, John Bowers, Matthew Dummer, Jonathan Klamkin</i>	
A 100-Gb/s PAM-4 Optical Receiver Integrated with All-Silicon Microring Avalanche Photodiode.....	15
<i>Inhyun Kim, Yuan Yuan, Ruida Liu, Hyungryul Kang, Ankur Kumar, Yiwei Peng, Dharma Paladugu, Hyeonseok Lee, Zhihong Huang, Chaerin Hong, Marco Fiorentino, Raymond Beausoleil, Samuel Palermo</i>	
Heterogeneous Integration of InGaAs PIN and APD Photodetectors for High-Speed Interconnects.....	17
<i>Matthew Dummer, Hongwei Zhao, Simone Suran Brunelli, Bei Shi, Michael McGiveny, Jonathan Klamkin</i>	

Author Index